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In The Claims

Please amend Claim 1 and add new Claim 17 as follows:

1. (Currently amended) An etching agent for etching copper in an etching process comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of about 10.01% to about 23.31% by weight of the etching agent, said etching agent etching the copper at an approximately uniform rate throughout the etching process.

2. (Original) An etching agent for copper according to Claim 1, wherein said aqueous solution contains acetic acid.

Claims 3-16 (Cancelled)

17. (New) An etching agent according to claim 1, wherein said etching agent is capable of selectively etching the copper.